

PMEG2005AELD

20 V, 0.5 A low V_F MEGA Schottky barrier rectifier

Rev. 1 — 10 May 2011

Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD882D leadless ultra small Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

1.2 Features and benefits

- Forward current: $I_F \leq 0.5$ A
- Reverse voltage: $V_R \leq 20$ V
- Low forward voltage: $V_F \leq 440$ mV
- Ultra small and leadless SMD plastic package
- AEC-Q101 qualified
- Solderable side pads
- Package height typ. 0.37 mm

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications
- Ultra high-speed switching

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$I_{F(AV)}$	average forward current	square wave; $\delta = 0.5$; $f = 20$ kHz					
		$T_{amb} \leq 85$ °C	[1]	-	-	0.5	A
		$T_{sp} \leq 130$ °C	-	-	-	0.5	A
I_R	reverse current	$V_R = 10$ V	-	300	600	μ A	
V_R	reverse voltage		-	-	20	V	
V_F	forward voltage	$I_F = 500$ mA	[2]	-	365	440	mV


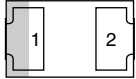
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm².

[2] Pulse test: $t_p \leq 300$ μ s; $\delta \leq 0.02$.



2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode	[1]	 sym001
2	anode	 Transparent top view	

[1] The marking bar indicates the cathode.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG2005AELD	-	leadless ultra small plastic package; 2 terminals; body 1 × 0.6 × 0.4 mm	SOD882D

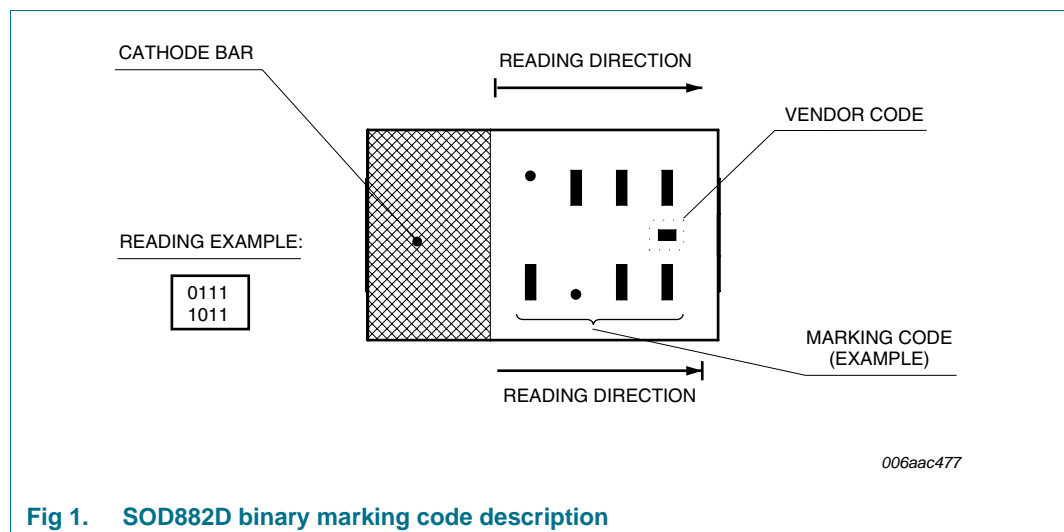
4. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
PMEG2005AELD	1001 0000

[1] For SOD882D binary marking code description, see [Figure 1](#).

4.1 Binary marking code description



5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
V_R	reverse voltage		-	20	V	
$I_{F(AV)}$	average forward current	square wave; $\delta = 0.5$; $f = 20$ kHz				
		$T_{amb} \leq 85$ °C	[1]	-	0.5	A
		$T_{sp} \leq 130$ °C	-	-	0.5	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ ms; $\delta \leq 0.25$	-	2.5	A	
I_{FSM}	non-repetitive peak forward current	square wave; $t_p = 8$ ms	[2]	-	3	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[3]	-	340	mW
			[1]	-	660	mW
			[4]	-	1000	mW
T_j	junction temperature		-	150	°C	
T_{amb}	ambient temperature		-55	+150	°C	
T_{stg}	storage temperature		-65	+150	°C	

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

[2] $T_j = 25$ °C prior to surge.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	-	370	K/W
			[1][3]	-	-	190	K/W
			[1][4]	-	-	125	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	50	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.
- [5] Soldering point of cathode tab.

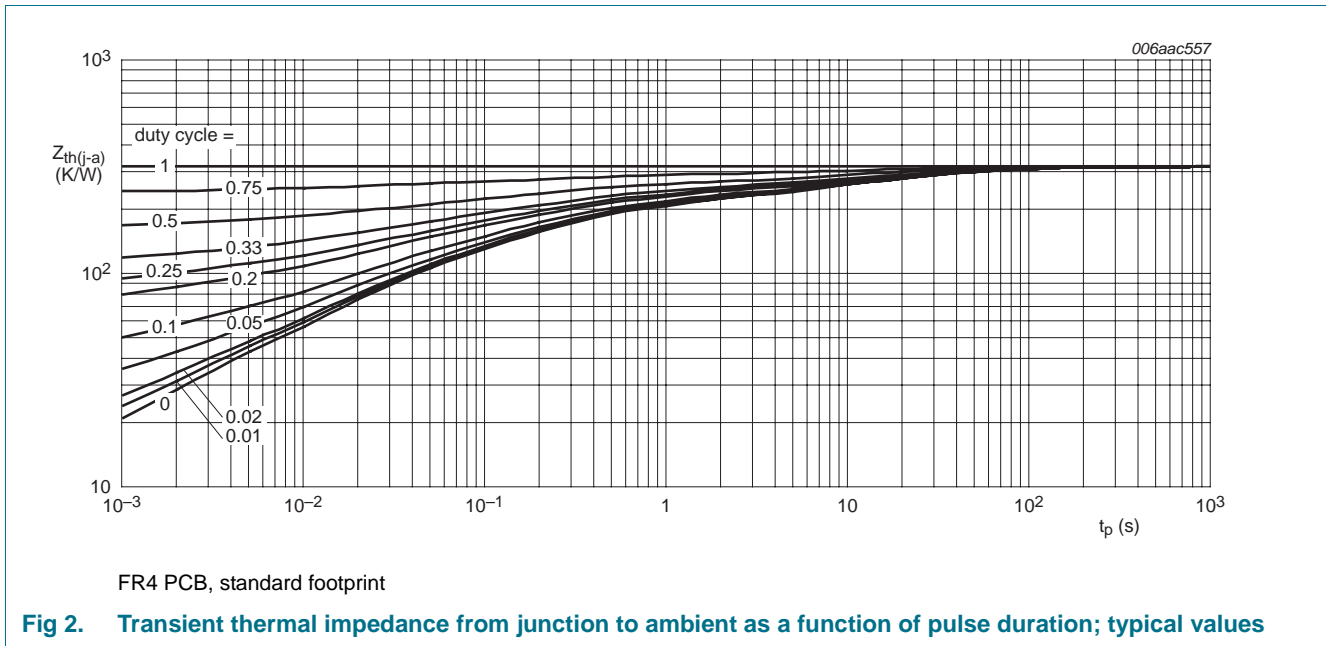
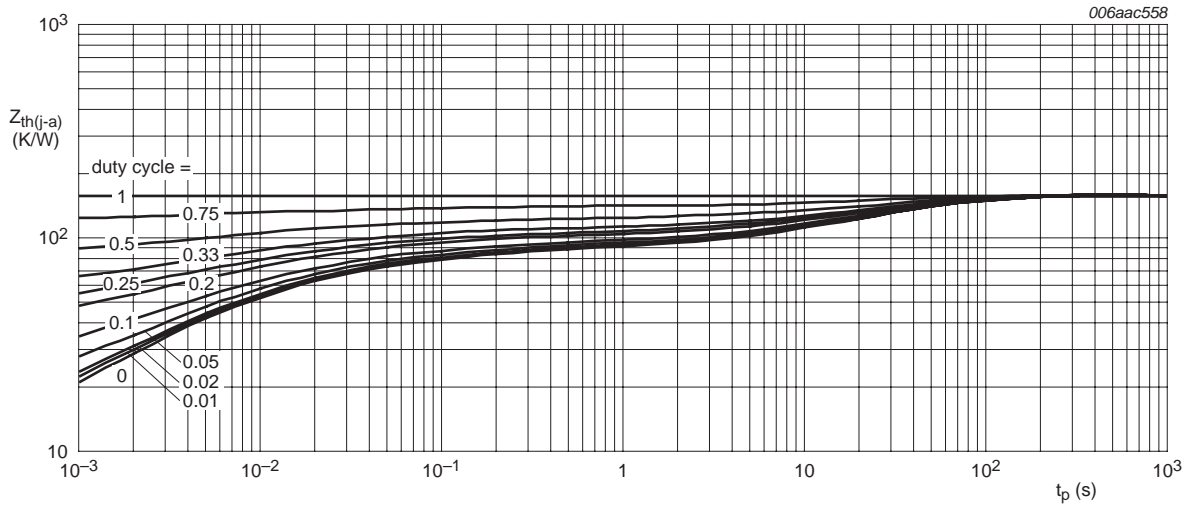
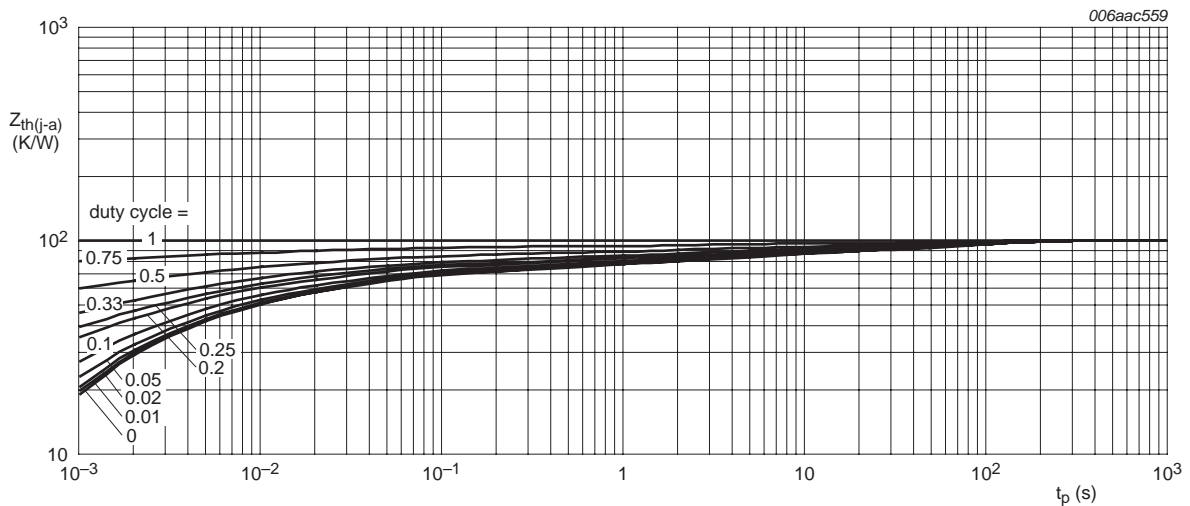


Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al₂O₃, standard footprint

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

7. Characteristics

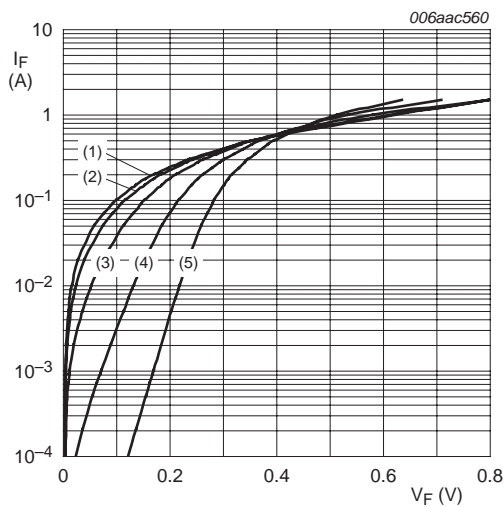
Table 7. Characteristics

$T_{amb} = 25\text{ }^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage		[1]			
		$I_F = 0.1\text{ mA}$	-	20	60	mV
		$I_F = 1\text{ mA}$	-	65	110	mV
		$I_F = 10\text{ mA}$	-	125	190	mV
		$I_F = 100\text{ mA}$	-	210	290	mV
I_R	reverse current	$V_R = 10\text{ V}$	-	300	600	μA
		$V_R = 20\text{ V}$	-	500	1500	μA
C_d	diode capacitance	$V_R = 1\text{ V}; f = 1\text{ MHz}$	-	19	25	pF
t_{rr}	reverse recovery time		[2]	6	-	ns

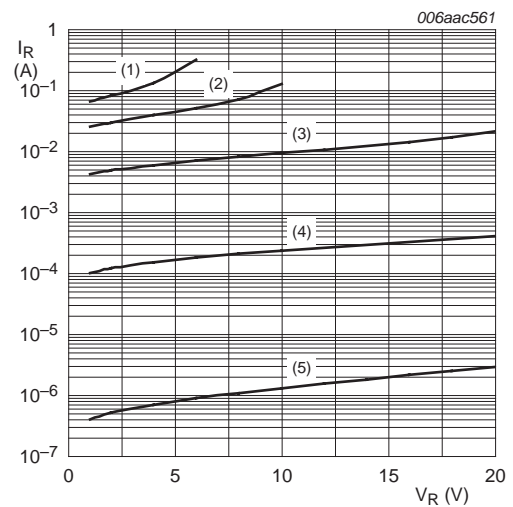
[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$.

[2] When switched from $I_F = 10\text{ mA}$ to $I_R = 10\text{ mA}; R_L = 100\text{ }\Omega$; measured at $I_R = 1\text{ mA}$.



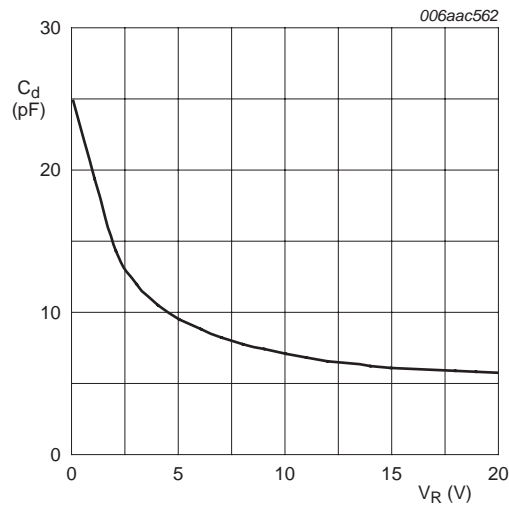
- (1) $T_j = 150\text{ }^\circ\text{C}$
- (2) $T_j = 125\text{ }^\circ\text{C}$
- (3) $T_j = 85\text{ }^\circ\text{C}$
- (4) $T_j = 25\text{ }^\circ\text{C}$
- (5) $T_j = -40\text{ }^\circ\text{C}$

Fig 5. Forward current as a function of forward voltage; typical values



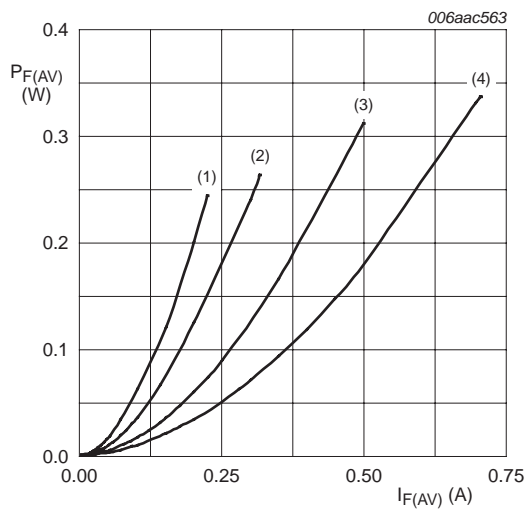
- (1) $T_j = 150\text{ }^\circ\text{C}$
- (2) $T_j = 125\text{ }^\circ\text{C}$
- (3) $T_j = 85\text{ }^\circ\text{C}$
- (4) $T_j = 25\text{ }^\circ\text{C}$
- (5) $T_j = -40\text{ }^\circ\text{C}$

Fig 6. Reverse current as a function of reverse voltage; typical values



$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

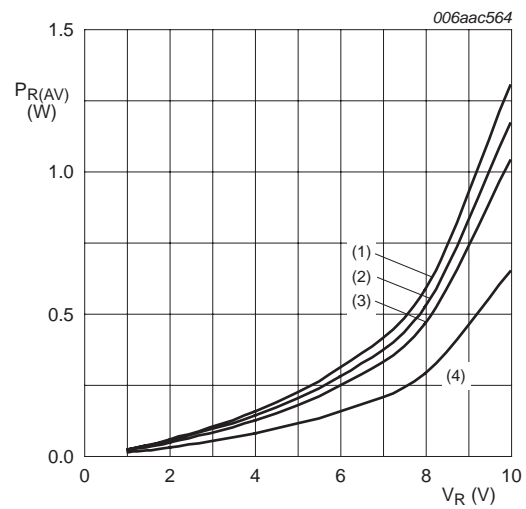
Fig 7. Diode capacitance as a function of reverse voltage; typical values



$T_j = 150 \text{ }^\circ\text{C}$

- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$

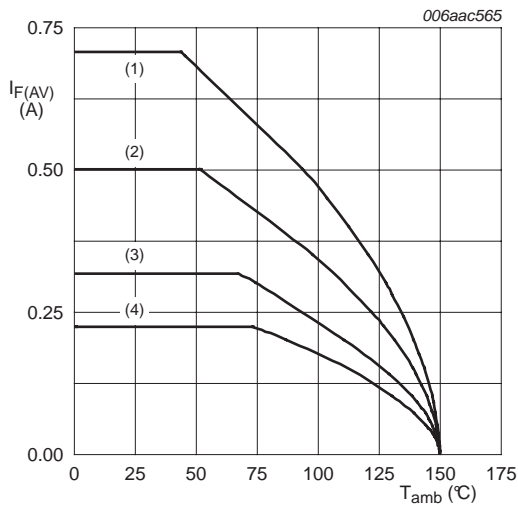
Fig 8. Average forward power dissipation as a function of average forward current; typical values



$T_j = 125 \text{ }^\circ\text{C}$

- (1) $\delta = 1$
- (2) $\delta = 0.9$
- (3) $\delta = 0.8$
- (4) $\delta = 0.5$

Fig 9. Average reverse power dissipation as a function of reverse voltage; typical values

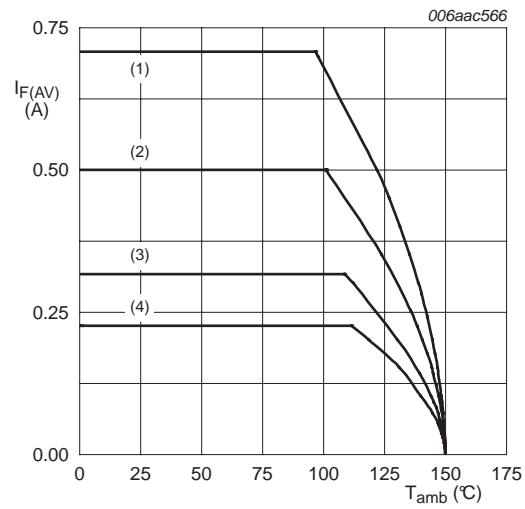


FR4 PCB, standard footprint

$T_j = 150\text{ °C}$

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20\text{ kHz}$
- (3) $\delta = 0.2$; $f = 20\text{ kHz}$
- (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 10. Average forward current as a function of ambient temperature; typical values

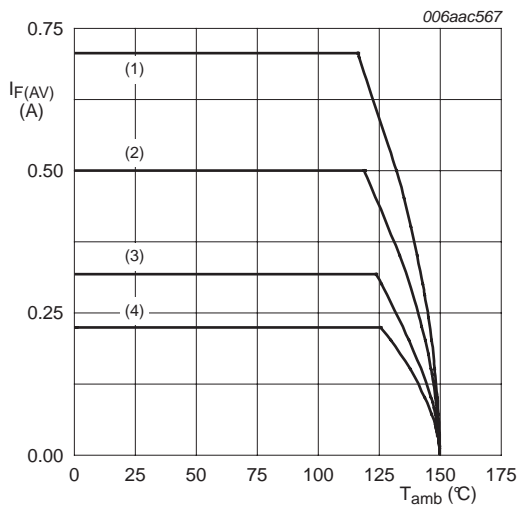


FR4 PCB, mounting pad for cathode 1 cm^2

$T_j = 150\text{ °C}$

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20\text{ kHz}$
- (3) $\delta = 0.2$; $f = 20\text{ kHz}$
- (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 11. Average forward current as a function of ambient temperature; typical values

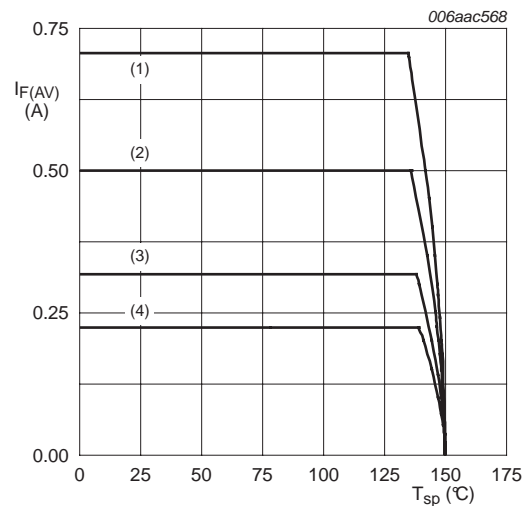


Ceramic PCB, Al_2O_3 , standard footprint

$T_j = 150\text{ °C}$

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20\text{ kHz}$
- (3) $\delta = 0.2$; $f = 20\text{ kHz}$
- (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 12. Average forward current as a function of ambient temperature; typical values

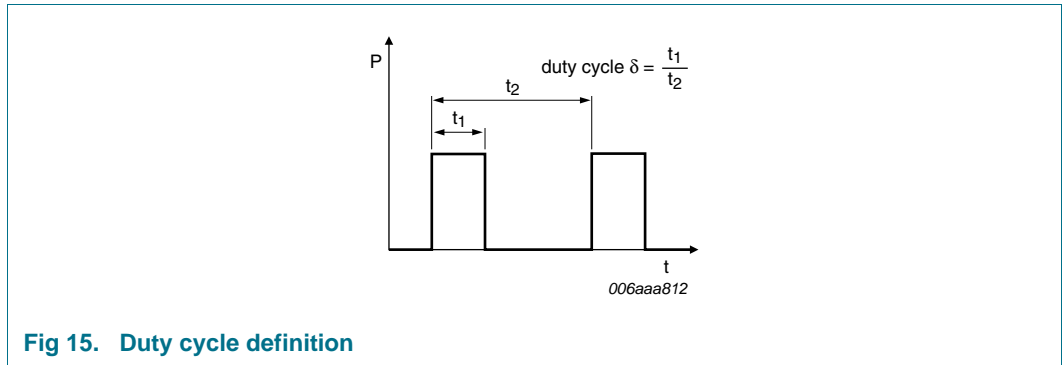
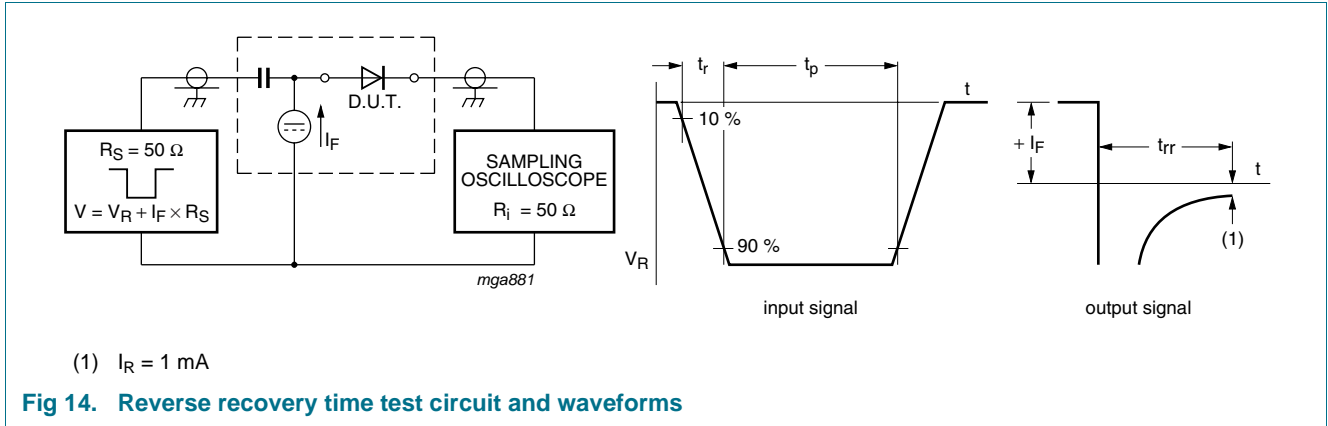


$T_j = 150\text{ °C}$

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20\text{ kHz}$
- (3) $\delta = 0.2$; $f = 20\text{ kHz}$
- (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 13. Average forward current as a function of solder point temperature; typical values

8. Test information

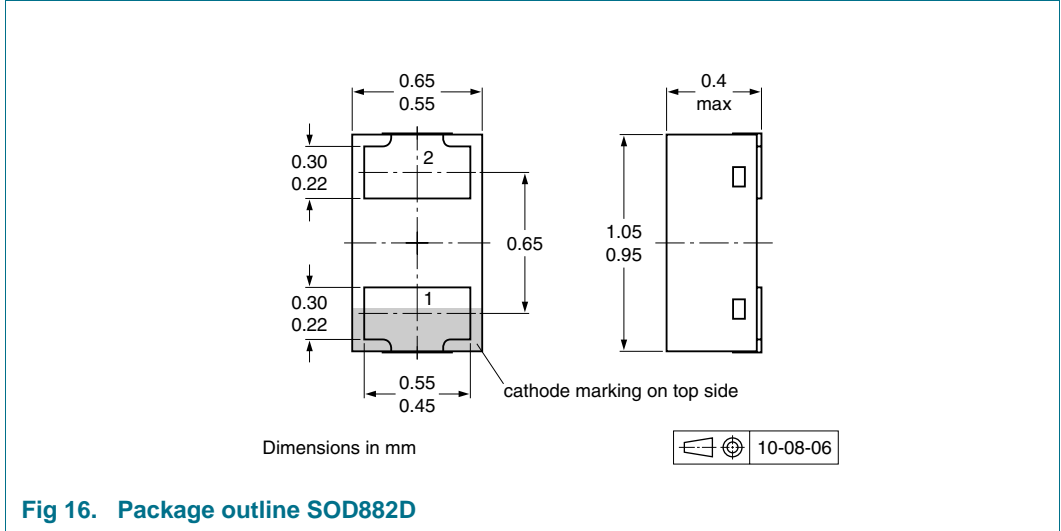


The current ratings for the typical waveforms as shown in [Figure 10](#), [11](#), [12](#) and [13](#) are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline



10. Packing information

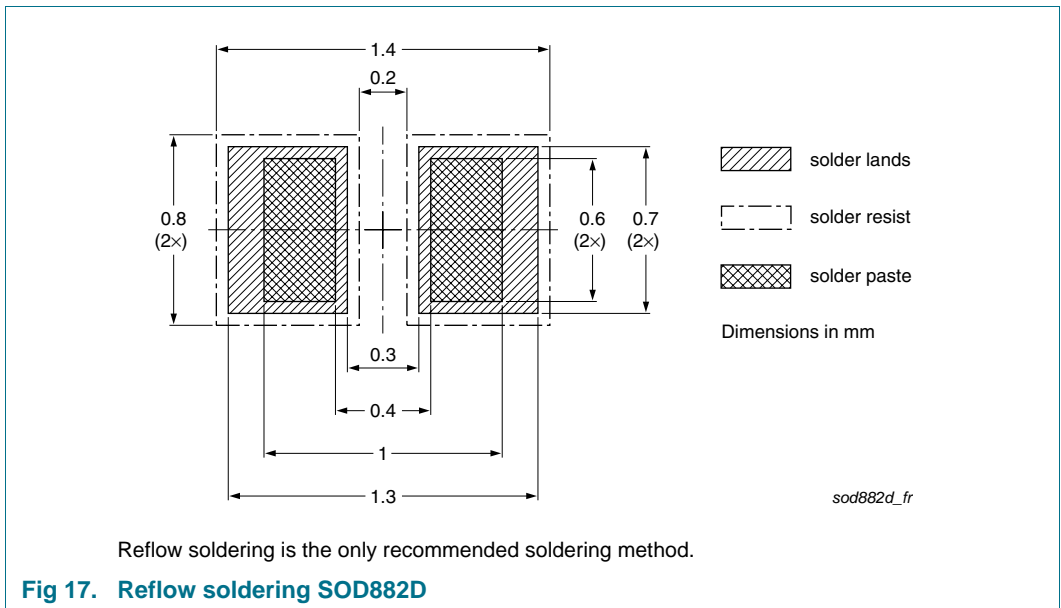
Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity
PMEG2005AELD	SOD882D	2 mm pitch, 8 mm tape and reel	10000 -315

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering



12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG2005AELD v.1	20110510	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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15. Contents

1 Product profile 1

1.1 General description 1

1.2 Features and benefits 1

1.3 Applications 1

1.4 Quick reference data 1

2 Pinning information 2

3 Ordering information 2

4 Marking 2

4.1 Binary marking code description 2

5 Limiting values 3

6 Thermal characteristics 4

7 Characteristics 6

8 Test information 9

8.1 Quality information 9

9 Package outline 10

10 Packing information 10

11 Soldering 10

12 Revision history 11

13 Legal information 12

13.1 Data sheet status 12

13.2 Definitions 12

13.3 Disclaimers 12

13.4 Trademarks 13

14 Contact information 13

15 Contents 14

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